



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION

20

© COPYRIGHT 20

BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.

LOC

DIST

REVISIONS

P

LTR

DESCRIPTION

DATE

DWN

APVD

A

REVISED FJ00-0399-02

20FEB02

KT

KK

B

REVISED EC: FJB0-103-04

04FEB04

Y.H

KK

C

REVISED FJB0-0183-04

20FEB04

H.T

K.K

1.1

Ø0.75 (吸着エリア)

-1: 本図

-1: AS SHOWN

プレス打ち抜き方向

0.8

2.2

0.6

1.6±0.1

2.1

0.1

1±0.1

3.2

0.75

0.5

0.2

0.15

1.9

1.3

0.6

0.6

0.9

参考パッド寸法

0.75

△1

メッキ仕様 (材料メッキ)

Ni UNDER PLATING: 0.8μm MIN
CONTACT POINT; Au 0.25~0.50μm
SOLDERING AREA; Au 0.05μm MIN

△2

カットバリ: 0.05MAX,

△3

その他全周バリ: 0.03MAX

◎4

ドライバック およびベーキングは不用のこと

△1

FINISH (PLATED MATERIAL)

Ni UNDER PLATING: 0.8μm MIN
CONTACT POINT; Au 0.25~0.50μm
SOLDERING AREA; Au 0.05μm MIN

△2

CUTTING BURR: 0.05MAX,

△3

CIRCUMFERENCE BURRS: 0.03MAX

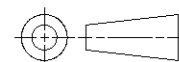
◎4

DISUSED PACKAGEING MATERIAL : DRYPACK AND BAKING PROCESS

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION
IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
SHOULD BE CONTACTED FOR THE LATEST REVISION.

DIMENSIONS:

mm

TOLERANCES UNLESS
OTHERWISE SPECIFIED:0 PLC ±0.2
1 PLC ±0.2
2 PLC ±0.2
3 PLC ±0.2
4 PLC ±0.2
ANGLES ±2

FINISH

SEE NOTE

MATERIAL

-

DWN 23AUG2001

K.TANAKA

CHK 23AUG2001

K.KODAIRA

APVD 23AUG2001

K.KODAIRA

PRODUCT SPEC

108-5786

APPLICATION SPEC

-

WEIGHT

-

CUSTOMER DRAWING

tyco
ElectronicsTyco Electronics AMP K.K.
Kawasaki, Japan

NAME

SHIELD FINGER 1608

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

00779

C=1565322

SCALE 20:1

SHEET

1

OF

2

REV

C

THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION

20

© COPYRIGHT 20

BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.

LOC

DIST

REVISIONS

P

LTR

DESCRIPTION

DATE

DWN

APVD

- SEE SHEET 1 OF 2

18.4 REF
12.4

Ø 330

PEELING ANGLE : 165°~180°

PEELING FORCE 0.1N~1.0N

© WEEDING THE COVER TAPE : 300MIN
(INCLUDED EMPTINESS POCKET)

→ DIRECTION OFF TOP OF REEL

4±0.1

4±0.1

Ø 1.55

1.75

2±0.1

12±0.3

5.5±0.1

トレーラ部
160mmMIN
WITHOUT CHARGE© 製品装填部
欠品無きことWITH PRODUCT CHARGE
NO STOCK-OUT IN POCKET
5,000EA/REEL

© 100MIN

キャリアテープ空部: 100mm以上
WITHOUT CHARGE

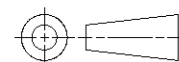
0.3

断面 A-A

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION.
IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
SHOULD BE CONTACTED FOR THE LATEST REVISION.

DIMENSIONS:

mm

TOLERANCES UNLESS
OTHERWISE SPECIFIED:0 PLC ±0.2
1 PLC ±0.2
2 PLC ±0.2
3 PLC ±0.2
4 PLC ±0.2
ANGLES ±2

MATERIAL

FINISH

DWN

K. TANAKA

23AUG01

CHK

K. KODAIRA

23AUG01

APVD

K. KODAIRA

23AUG01

PRODUCT SPEC

APPLICATION SPEC

WEIGHT

-

CUSTOMER DRAWING

tyco
ElectronicsTyco Electronics AMP K.K.
Kawasaki, Japan

NAME

SHIELD FINGER 1608

SIZE

A3

00779

CAGE CODE

C=1565322

DRAWING NO

RESTRICTED TO

-

SCALE 20:1

SHEET 2 OF 2

REV C